

### Applied Research Grants

<i>Number</i>	<i>Principal Investigator</i>	<i>Project Title</i>	<i>Start</i>	<i>End</i>	<i>Total Fund</i>
<b>Central Allocation Vote</b>					
8730010	Edward Kai-Ning YUNG	A Near-field Measurement System for Wireless Communications Antennas	1-Oct-00	30-Sep-02	<b>\$2,600,000</b>
<b>Collaborated Research Center</b>					
8720003	Archie Yan-cheong CHAN	CRC on Conductive Adhesive Technology for High Density Electronic Packaging	1-Jan-00	30-Jun-04	<b>\$2,296,045</b>
<b>Industry and Technology Fund</b>					
9440006	Archie Yan-cheong CHAN	Conductive Adhesive Technology Programme for Fine Pitch Electronic Interconnect	1-Dec-00	30-Nov-04	\$7,845,000
9440040	Edward Kai-Ning YUNG	Development of RFID Readers	1-Mar-05	28-Feb-06	\$5,100,000
9440027	Archie Yan-cheong CHAN	Study on Flip Chip Bonding Solutions for Fine Pitch Chip-on-film (COF) Package	1-Dec-02	30-Nov-04	\$373,888
9440025	Archie Yan-cheong CHAN	Characterization on the Thermal, Mechanical, Electrical and Optical Properties of Selected Materials for Active Photonic Component Packaging Application	1-Sep-02	31-Aug-04	\$370,000
9440035	Archie Yan-cheong CHAN	A Detailed Study of Enhanced Lead Free SnAgCu (i.e. SnAgCuIn) Solder Reliability and Wetting Ability for Surface Mounting Application	1-Oct-04	30-Sep-06	\$370,000
9440030	Archie Yan-cheong CHAN	Study on Non Conductive Paste Bonding for Fine Pitch Flip Chip Interconnection	1-Sep-03	31-Aug-05	\$370,000
				<b>Total</b>	<b>\$14,428,888</b>
<b>Teaching and development Grant</b>					
TDG0046	Chi-hou CHAN	Industrial Attachment Scheme: A Fully Integrated Programme and Rewarding Professional Experience	1-Sep-02	31-Aug-05	\$6,700,000
TDG0049	Chi-hou CHAN	Staff Development & Enhancement: In Support of Industrial Attachment Scheme	1-Jan-04	31-Aug-05	\$1,000,000
				<b>Total</b>	<b>\$7,700,000</b>